

SPECIFICATION FOR LCD MODULE

MODULE NO: AFV128160A00-1.7N6NTN REVISION NO: 02

	SIGNATURE	DATE
PREPARED BY (RD ENGINEER)		
CHECKED BY		
APPROVED BY		

Customer's Approval:

REVISION RECORD

REV NO.	REV DATE	CONTENTS	REMARKS
V0.1	2012-03-29	First release	Preliminary
V0.2	2012-11-26	EXTERNAL DIMENSIONS	Change the driver IC

CONTENTS

■GENERAL INFORMATION	4
■ ABSOLUTE MAXIMUM RATINGS	۷
■ ELECTRICAL CHARACTERISTICS	4
■BACKLIGHT CHARACTERISTICS	5
■EXTERNAL DIMENSIONS	6
■ELECTRO-OPTICAL CHARACTERISTICS	7
■INTERFACE DESCRIPTION	9
■AC CHARACTERISTICS	10
■POWER SEQUENCE	13
RELIABILITY TEST CONDITIONS	14
INSPECTION CRITERION	15

■ GENERAL INFORMATION

Item of general information	Contents	Unit
LCD size	1.77 inch (Digital)	/
LCD type	TFT/TRANSMISSIVE normal white	
View direction	6 o'clock	
Gray scale inversion direction	12 o'clock	
Resolution	128*3(RGB)*160	
Module size $(W \times H \times T)$	34(W)×48.7(H)×2.4(D)	mm ³
Active area (W×H)	28.03(H)×35.04(V)	mm ²
Pixel pitch (W × H)	0.219(H)×0.219(V)	mm ²
Interface Type	8080 parallel interface	/
Input voltage	2.8V	V
Module Power consumption	TBD	mw
Backlight Type	2 *LED	/

■ ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Min	Max	Unit
Power supply voltage	DVDD	-0.3	3.6	V
Logic Signal Input Level	Vi	-0.3	DVDD+0.3	V
Operating temperature	Тор	-20	70	°C
Storage temperature	TST	-30	80	°C
Humidity	RH	-	90%(Max60 °C)	RH

■ ELECTRICAL CHARACTERISTICS

DC CHARACTERISTICS

Parameter	Symbol	Min	Тур	Max	Unit
Supply Voltage	VDD	2.5	2.8	3.6	V
VCOM	VCOM	-1.5	3.3	3.5	V
	IVDD	-	4.0	10	mA
Cument of novyon quanty	IAVDD	-	20	50	mA
Current of power supply	IGH	-	0.2	1.0	mA
	IGL	-	0.2	1.0	mA
Input voltage 'H' level	VIH	0.7DVDD	-	VDD	V
Input voltage 'L' level	VIL	0	-	0.3VDD	V

Note:Be sure to apply DVDD and VGL to the LCD first , then apply VGH.

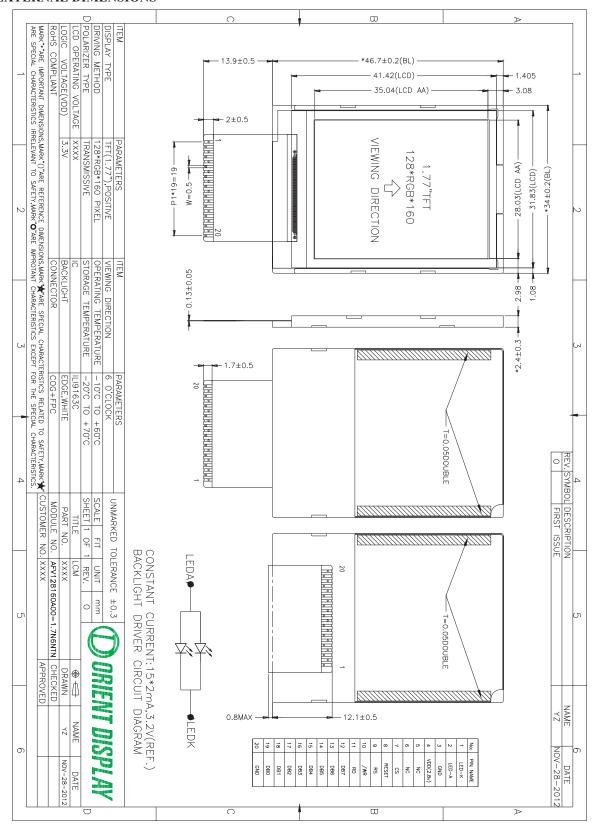
■ BACKLIGHT CHARACTERISTICS

Item of backlight characteristics	Symbol	Min.	Тур.	Max.	Unit	Condition
Forward voltage	Vf	-	3.2	3.5	V	Note 1
Current for LED backlight	IL	-	40	-	mA	
LED life time	-	20,000	-	-	-	Note 2

Note 1: The LED Supply Voltage is defined by the number of LED at Ta=25°C and IL =40mA.

Note 2: The "LED life time" is defined as the module brightness decrease to 50% original brightness at $Ta=25^{\circ}C$ and IL=40mA. The LED lifetime could be decreased if operating IL is larger than 40 mA.

■ EXTERNAL DIMENSIONS



■ ELECTRO-OPTICAL CHARACTERISTICS

Item of electro-optical characteristics	Symbol	Condition	Min	Тур	Max	Unit	Remark	Note
Response time	Tr+ Tf		_	25	50	ms	Fig.1	4
Contrast ratio	Cr		400	500	_		FIG 2.	1
Luminance uniformity	δ WHITE	70	160	75	_	%	FIG 2.	3
Surface Luminance	Lv		170	220	_	cd/m ²	FIG 2.	2
		Ø = 90°	50	60	_	deg	FIG 3.	
Viewing angle	θ	Ø = 270°	50	60	_	deg	FIG 3.	
range	l A	$\emptyset = 0$ °	50	60	_	deg	FIG 3.	6
		Ø = 180°	45	50	_	deg	FIG 3.	
	Red x		0.5550	0.6050	0.6550	-		
	Red y		0.3160	0.3660	0.4160	-		
	Green x	$\theta=0^{\circ}$	0.3094	0.3594	0.4094	-		
CIE (x, y)	Green y	Ø=0°	0.5030	0.5530	0.6030	-	FIG 2.	5
chromaticity	Blue x	Ta=25°C	0.1064	0.1564	0.2064	-	FIG 2.	3
	Blue y	1a-23 C	0.1066	0.1566	0.2066	-		
	White x		0.2578	0.3178	0.3778	-		
	White y		0.2943	0.3543	0.4143	-		

Note1. Contrast Ratio(CR) is defined mathematically by the following formula. For more information see FIG 2.:

Contrast Ratio = Average Surface Luminance with all white pixels (P 1,P2, P 3,P4, P5)

Average Surface Luminance with all black pixels (P1, P2, P 3,P4, P5)

Note2. Surface luminance is the LCD surface from the surface with all pixels displaying white. For more information see FIG 2.

Lv = Average Surface Luminance with all white pixels (P1, P2, P3,P4, P5)

Note3. The uniformity in surface luminance (δ WHITE) is determined by measuring luminance at each test position 1 through 5, and then dividing the maximum luminance of 5 points luminance by minimum luminance of 5 points luminance. For more information see FIG 2.

$\delta \text{ WHITE} = \frac{\text{Minimum Surface Luminance with all white pixels } (P_1, P_2, P_3, P_4, P_5)}{\text{Maximum Surface Luminance with all white pixels } (P_1, P_2, P_3, P_4, P_5)}$

Note4. Response time is the time required for the display to transition from White to black(Rise Time, Tr) and from black to white(Decay Time, Tf). For additional information see FIG 1..

Note5. CIE (x, y) chromaticity ,The x,y value is determined by screen active area position NO.5 For more information see FIG 2.

Note6. Viewing angle is the angle at which the contrast ratio is greater than 2. For TFT module the conrast ratio is greater than 10. The angles are determined for the horizontal or x axis and the vertical or y axis with respect to the z axis which is normal to the LCD surface. For more information see FIG 3.

Note7. For Viewing angle and response time testing, the testing data is base on Autronic-Melchers's ConoScope. Series Instruments. For contrast ratio, Surface Luminance, Luminance uniformity and CIE, the testing data is base on TOPCON's BM-5 photo detector or compatible.

Note8. For TFT module, Gray scale reverse occurs in the direction of panel viewing angle

FIG.1. The definition of Response Time

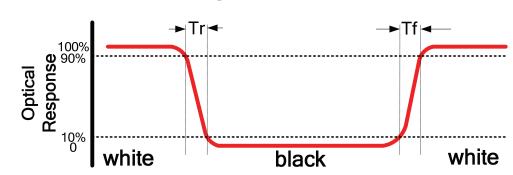


FIG.2. Measuring method for Contrast ratio, surface luminance, Luminance uniformity, CIE (x, y) chromaticity

A: 5 mm B: 5 mm

H,V: Active Area

Light spot size ∅=5mm, 500mm distance from the LCD surface to detector lens

measurement instrument is TOPCON's luminance meter BM-5

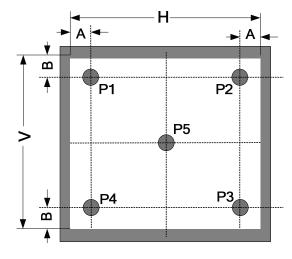
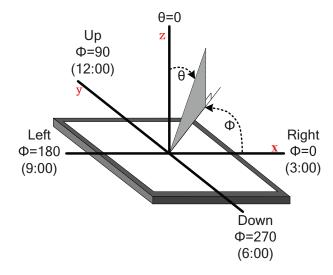


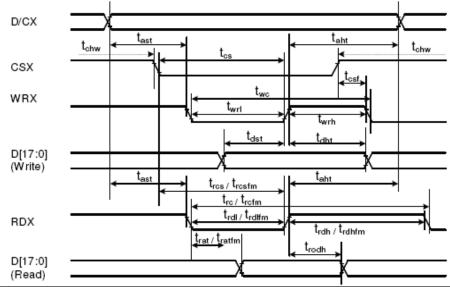
FIG.3. The definition of viewing angle



■ INTERFACE DESCRIPTION

Interface NO.	NAME	I/O or connect to	DESCRIPTION
1	LED-K	P	LED-
2	LED-A	P	LED+
3	GND	P	Ground
4	VDD	P	Power supply(2.8V)
5	NC	/	/
5	NC	/	/
7	CS	I	Chip select
8	RESET	I	Reset signal
9	RS	I	Parament/command signal
10	WR	I	Write signal
11	RD	I	Read signal
12	DB7	I/O	Data
13	DB6	I/O	Data
14	DB5	I/O	Data
15	DB4	I/O	Data
16	DB3	I/O	Data
17	DB2	I/O	Data
18	DB1	I/O	Data
19	DB0	I/O	Data
20	GND	P	Ground

■ AC CHARACTERISTICS

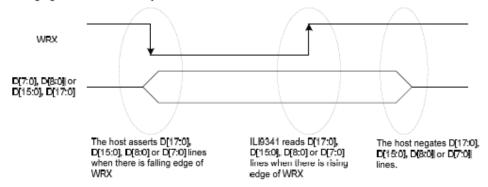


Signal	Symbo I	Parameter	min	max	Unit	Description
DCX tast		Address setup time	0	-	ns	
DCX	taht	Address hold time (Write/Read)	0	-	ns	
	tchw	CSX "H" pulse width	0	-	ns	
	tcs	Chip Select setup time (Write)	15	-	ns	
CSX	trcs	Chip Select setup time (Read ID)	45	-	ns	
	tresfm	Chip Select setup time (Read FM)	355	-	ns	
	tcsf	Chip Select Wait time (Write/Read)	10	-	ns	
	twc	Write cycle	66	-	ns	
WRX	twrh	Write Control pulse H duration	15	-	ns	
	twrl	Write Control pulse L duration	15	-	ns	
	trcfm	Read Cycle (FM)	450	-	ns	
RDX (FM)	trdhfm	Read Control H duration (FM)	90	-	ns	
	trdlfm	Read Control L duration (FM)	355	-	ns	
	trc	Read cycle (ID)	160	-	ns	
RDX (ID)	trdh	Read Control pulse H duration	90	-	ns	
	trdl	Read Control pulse L duration	45	-	ns	
D(47.0)	tdst	Write data setup time	10	-	ns	
D[17:0], D[17:10]&D[8:1],	tdht	Write data hold time	10	-	ns	For maximum CL=30pF
	trat	Read access time	-	40	ns	For minimum CL=30F
D[17:10], D[17:9]	tratfm	Read access time	-	340	ns	For Hillindin CL=8pF
الو: ١٠١	trod	Read output disable time	20	80	ns	

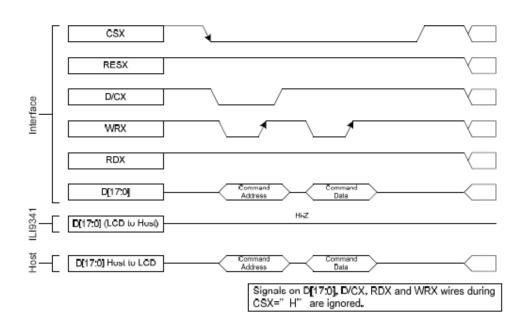
Note: Ta = -30 to 70 °C, VDDI=1.65V to 3.3V, VCI=2.5V to 3.3V, VSS=0V.

WriteCycle Sequence

The following figure shows a write cycle for the 8080- I MCU interface.

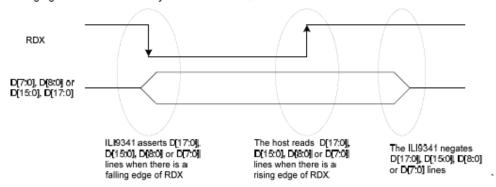


Note: WRX is an unsynchronized signal (It can be stopped)

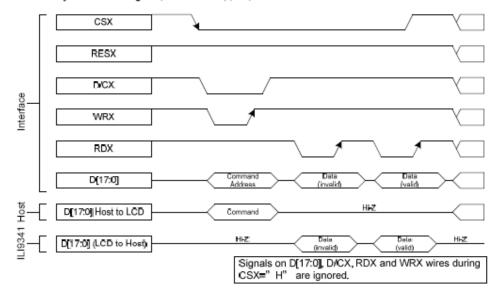


Read cycle sequnce

The following figure shows the read cycle for the 8080- I MCU interface.



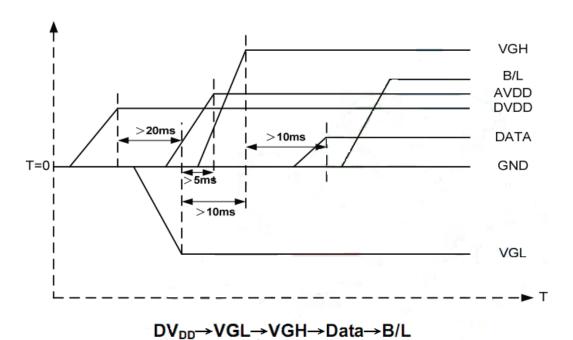
Note: RDX is an unsynchronized signal (It can be stopped).



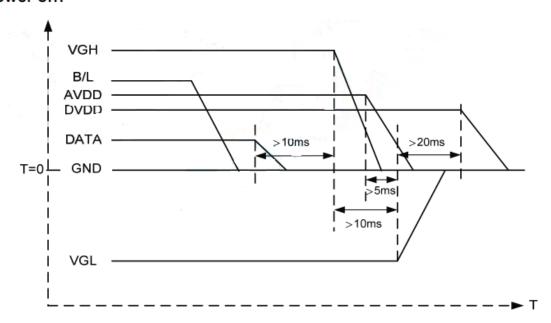
Note: Read data is only valid when the D/CX input is pulled high. If D/CX is driven low during read then the display information outputs will be High-Z.

■ POWER SEQUENCE

a. Power on:



b. Power off:



B/L→Data→VGH→VGL→DV_{DD}

Note: Data include R0~R7, B0~B7, GO~G7, U/D, L/R, DCLK, HS,VS,DE.

■ RELIABILITY TEST CONDITIONS

No.	Test Item	Test Condition	Inspection after test
1	High Temperature Storage	80 ± 2 °C/240 hours	
2	Low Temperature Storage	-30 ± 2 °C/240 hours	
3	High Temperature Operating	70 ± 2 °C/120 hours	T
4	Low Temperature Operating	-20 ± 2 °C/120 hours	Inspection after 2~4hours storage at
5	Temperature Cycle	-20±2°C~25~70±2°C × 10 cycles (30 min.) (5 min.) (30 min.)	2~4hours storage at room temperature, the sample shall be free from
6	Damp Proof Test	$50^{\circ}\text{C} \pm 5^{\circ}\text{C} \times 90\%\text{RH}/120 \text{ hours}$	defects:
7	Vibration Test	Frequency: 10Hz~55Hz~10Hz Amplitude: 1.5mm, X, Y, Z direction for total 3hours (Packing condition)	1.Air bubble in the LCD; 2.Sealleak; 3.Non-display; 4.missing segments;
8	Dropping test	Drop to the ground from 1m height, one time, every side of carton. (Packing condition)	5.Glass crack; 6.Current Idd is twice higher than initial value.
9	ESD test	Voltage:±8KV R: 330Ω C: 150pF Air discharge, 10time	

Remark:

- 1. The test samples should be applied to only one test item.
- 2. Sample size for each test item is 5~10pcs.
- 3. For Damp Proof Test, Pure water(Resistance \geq 10M Ω) should be used.
- 4.In case of malfunction defect caused by ESD damage, if it would be recovered to normal state after resetting, it would be judged as a good part.
- 5.EL evaluation should be excepted from reliability test with humidity and temperature: Some defects such as black spot/blemish can happen by natural chemical reaction with humidity and Fluorescence EL has
- 6.Failure Judgment Criterion: Basic Specification, Electrical Characteristic, Mechanical Characteristic, Optical Characteristic.

■ INSPECTION CRITERION

This specification is made to be used as the standard acceptance/rejection criteria for Normal LCM Product.

1 Sample plan

Sampling plan according to GB/T2828.1-2003/ISO 2859-1: 1999 and ANSI/ASQC Z1.4-1993, normal level 2 and based on:

Major defect: AQL 0.65 Minor defect: AQL 1.5

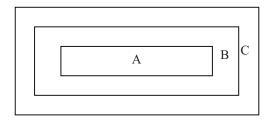
2. Inspection condition

• Viewing distance for cosmetic inspection is about 30cm with bare eyes, and under an environment of $20\sim40$ W light intensity, all directions for inspecting the sample should be within 45° against perpendicular line. (Normal temperature $20\sim25^{\circ}$ C and normal humidity $60\pm15^{\circ}$ RH).

Driving voltage

The Vop value from which the most optimal contrast can be obtained near the specified Vop in the specification (Within ± 0.5 V of the typical value at 25°C.).

3. Definition of inspection zone in LCD.



Zone A: character/Digit area

Zone B: viewing area except Zone A (ZoneA+ZoneB=minimum Viewing area)

Zone C: Outside viewing area (invisible area after assembly in customer's product)

Fig.1 Inspection zones in an LCD.

Note: As a general rule, visual defects in Zone C are permissible, when it is no trouble for quality and assembly of customer's product.

4.Inspection Standard

4.1 Major Defect

Item No	Items to be inspected	Inspection Standard	Classification of defects
4.1.1	All functional defects	 No display Display abnormally Missing vertical, horizontal segment Short circuit Back-light no lighting, flickering and abnormal lighting. 	
4.1.2	Missing	Missing component	Major
4.1.3	Outline dimension	Overall outline dimension beyond the drawing is not allowed.	

4.2 Cosmetic Defect

4.2.1 Module Cosmetic Criteria

No.	Item	Judgement Criterion	Partition
1	Difference in Spec.	None allowed	Major
2	Pattern peeling	peeling No substrate pattern peeling and floating	
3	Soldering defects	No soldering missing	Major
		No soldering bridge	Major
		No cold soldering	Minor
4	Resist flaw on Printed Circuit Boards	visible copper foil (Ø0.5mm or more) on substrate pattern	Minor
5	Accretion of metallic	No accretion of metallic foreign matters (Not exceed Ø0.2mm)	Minor
	Foreign matter	, , , , , , , , , , , , , , , , , , ,	Minor
6	Stain	No stain to spoil cosmetic badly	Minor
7	Plate discoloring	No plate fading, rusting and discoloring	Minor
8	Solder amount	a. Soldering side of PCB	Minor
	1. Lead parts	Solder to form a 'Filet' all around the lead. Solder should not hide the lead form perfectly. (too much) b. Components side (In case of 'Through Hole PCB') Solder to reach the Components side of PCB.	
	2. Flat packages	Either 'Toe' (A) or 'Seal' (B) of the lead to be covered by 'Filet'. Lead form to be assume over solder.	Minor
	3. Chips	$(3/2) H \ge h \ge (1/2) H$	Minor

9	Solder ball/Soldersplash	the conductor or solder pad h≥0.13mm The diameter of solder ball d≤0.15mm. b. The quantity of solder balls or solder Splashes isn't beyond 5 in 600 mm². c. Solder balls/Solder splashes do not violate minimum electrical clearance. d. Solder balls/Solder splashes must be entrapped/encapsulated Or attached to the metal surface. NOTE: Entrapped/encapsulated/attached is intended to mean	Minor Minor Major Minor
		NOTE: Entrapped/encapsulated/attached is intended to mean that normal service environment of the product will not cause a solder ball to become dislodged.	

4.2.2Cosmetic Criteria (Non-Operating)

No.	Defect	Judgment Criterion			
1	Spots	In accordance with Screen Cosmetic Criteria (Operating) No.1.			
2	Lines	In accordance with Screen Cosmetic Criteria (Operating) No.2.			
3	Bubbles in polarizer				
		Size : d mm	Acceptable Qty in active area		
		d ≤ 0.3	Disregard		
		$0.3 < d \le 1.0$	3		
		$1.0 < d \le 1.5$	1		
		1.5 < d	0		
4	Scratch	In accordance with spots and lines operating cosmetic criteria. When the			
		light reflects on the panel surface, the scratches are not to be remarkable.			
5	Allowable density	Above defects should be separated more than 30mm each other.			
6	Coloration	Not to be noticeable coloration in the viewing area of the LCD panels.			
		Back-lit type should be judged with back-lit on state only.			
7	Contamination	Not to be noticeable.			

4.2.3 Cosmetic Criteria (Operating)

No.	Defect		Judgment Cri	terion	Partition
1	Spots	A) Clear			Minor
		Lcd size	Size : d mm	Acceptable Qty in active area	
		Led Size	d≤0.1	Disregard	
		Lcd	$0.1 < d \le 0.2$	Disregard 6	
		size≤8.0'	$0.1 < d \le 0.2$ $0.2 < d \le 0.3$	2	
			$0.2 < d \le 0.3$ 0.3 < d	0	
			d ≤0.1	Disregard	
		Lcd size>8.0'	$0.1 < d \le 0.3$	10	
			$0.3 < d \le 0.5$	5	
			0.5 < d	0	
			ective point sha	re dots which must be within one ll not exceed 6 pcs no more than an 8 inch LCD.	
		Lcd size	Size : d mm	Acceptable Qty in active area	
			d≤0.2	Disregard	
		Lcd size≤	0.2 <d≤0.5< td=""><td>6</td><td></td></d≤0.5<>	6	
		8.0'	0.5 <d≤0.7< td=""><td>2</td><td></td></d≤0.7<>	2	
			0.7 <d< td=""><td>0</td><td></td></d<>	0	
			d≤0.2	Disregard	
			0.2≤d≤0.5	10	
		Lcd size $>$ 8.0'	0.5≤d≤0.7	3	
			0.7 <d≤1.0< td=""><td>1</td><td></td></d≤1.0<>	1	
			1.0< d	0	
		inch LCD and 10PCS for		exceed 6 pcs for no more than 8 ch LCD.	
2	Lines	A) Clear	(0)		Minor
			(0)		
		2.0 (6)		See No. 1	
			0.1	W	
		0.02 0.0		L	
	Note: () - Acceptable Qty in active area				
		L - Length (mm) W - Width (mm)			
		∞ - Disregard			
		B) Unclear			
		L H		(0)	
		∞ (6)		
		2.0		See No. 1	
		0.05	0.3	0.5 W	
		'Clear' = The shade and 'Unclear' = The shade and shade	nd size are not ch size are changed		

3	Rubbing line	Not to be noticeable.	Minor	
4	Allowable density	Above defects should be separated more than 10mm each other.	Minor	
5	Rainbow	Not to be noticeable.	Minor	
6	Dot size	To be 95% ~ 105% of the dot size (Typ.) in drawing. Partial defects of each dot (ex. pin-hole) should be treated as 'Spot'. (see <i>Screen Cosmetic Criteria (Operating) No.1</i>)		
7	Uneven brightness (only back-lit type module)		Minor	
		O : Measuring points		

Note:

- (1) Size : d = (long length + short length) / 2
- (2) The limit samples for each item have priority.
- (3) Complex defects are defined item by item, but if the numbers of defects are defined in above table, the total number should not exceed 10.
- (4) In case of 'concentration', even the spots or the lines of 'disregarded' size should not allowed. Following three situations should be treated as 'concentration'.
 - 7 or over defects in circle of Ø5mm.
 - 10 or over defects in circle of Ø10mm.
 - 20 or over defects in circle of Ø20mm.